

Title (en)

APPARATUS AND METHOD FOR DRYING METAL CHIPS BEFORE PROCESSING IN MOLDING SYSTEM

Title (de)

VORRICHTUNG UND VERFAHREN ZUM TROCKNEN VON METALLSPÄNEN VOR DER VERARBEITUNG IN EINEM FORMSYSTEM

Title (fr)

APPAREIL ET PROCEDE PERMETTANT DE SECHER DES COPEAUX METALLIQUES AVANT TRAITEMENT DANS UN SYSTEME DE MOULAGE

Publication

EP 2076343 A1 20090708 (EN)

Application

EP 07815807 A 20070913

Priority

- CA 2007001603 W 20070913
- US 53816006 A 20061003

Abstract (en)

[origin: US2008079202A1] Disclosed is: (i) a sub-system of a metal molding system, including (amongst other things) a conditioner, (ii) a metal molding system, including a conditioner, (iii) a metallic molded article manufactured by the use of a metal molding system having a conditioner, (iv) a method of a metal molding system, comprising conditioning, at least in part, metal chips, (v) a metallic molded article manufactured by the use of a method of a metal molding system, including conditioning, at least in part, metal chips, (vi) a molding material, including metal chips being conditioned, at least in part, (vii) a molten molding material, including a molten metallic melt being made from metal chips being conditioned, at least in part, and/or (viii) a metallic molded article, including a solidified molding material having been made from metal chips being conditioned, at least in part, amongst other things.

IPC 8 full level

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CPC (source: EP US)

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